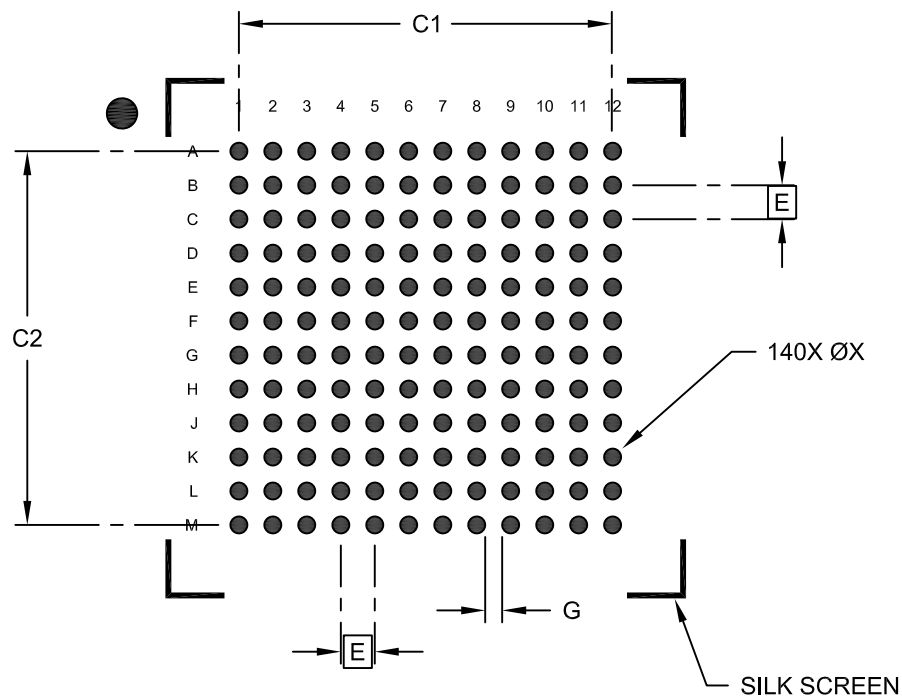


144-Lead Thin Fine-Pitch Ball Grid Array Package (B4B) - 10x10x1.2 mm Body [TFBGA]
Atmel Legacy GPC: CGQ

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.80 BSC		
Optional Pad Diameter (X247)	X			0.30
Contact Pad Spacing	C1		8.80	
Contact Pad Spacing	C2		8.80	
Column and Row Spacing	G	0.40		

Notes:

- Dimensioning and tolerancing per ASME Y14.5M
BSC: Basic Dimension. Theoretically exact value shown without tolerances.
- For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during reflow process